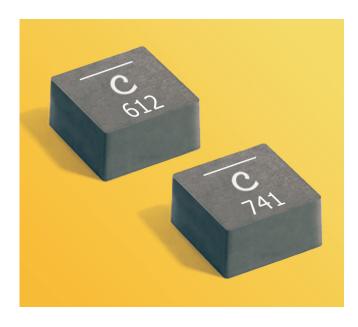
High Reliability Power Inductors MS619PYA



- High temperature materials allow operation in ambient temperatures up to 155°C
- Tin-lead (Sn-Pb) termination for the best possible board
- High current and very low DCR
- Soft saturation makes them ideal for VRM/VRD applications.

Core material Composite

Terminations Tin-lead (63/37) over copper.

Weight 9.5 - 11.7 g

Ambient temperature -55°C to +105°C with Irms current.

Maximum part temperature +155°C (ambient + temp rise).

Storage temperature Component: -55°C to +155°C.

Tape and reel packaging: -55°C to +80°C

Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C / 85% relative humidity)

Enhanced crush-resistant packaging 300/13" reel Plastic tape: 32 mm wide, 0.3 mm thick, 24 mm pocket spacing, 8.26 mm pocket depth

	Inductance ²	DCR (mOhms)3		SRF (MHz) ⁴		Isat⁵	Irms (A) ⁶	
Part number ¹	±20% (μH)	typ	max	min	typ	(A)	20°C rise	40°C rise
MS619PYA401MSZ	0.40	0.50	0.70	42.4	53.0	111	35.3	45.0
MS619PYA741MSZ	0.74	0.72	0.86	28.1	35.1	86.0	32.4	44.8
MS619PYA102MSZ	1.0	0.93	1.12	24.0	30.0	73.5	30.5	43.1
MS619PYA132MSZ	1.3	1.15	1.38	21.0	26.2	65.0	26.0	35.0
MS619PYA182MSZ	1.8	1.61	1.93	17.0	21.3	57.0	24.9	32.9
MS619PYA202MSZ	2.0	1.91	2.29	16.1	20.1	51.0	22.1	29.9
MS619PYA302MSZ	3.0	2.62	3.10	12.8	16.0	43.0	19.2	25.8
MS619PYA452MSZ	4.5	3.82	4.58	10.0	12.5	34.2	15.3	20.3
MS619PYA532MSZ	5.3	4.35	5.22	9.4	11.8	33.0	14.6	19.9
MS619PYA612MSZ	6.1	5.66	6.79	9.4	11.7	31.0	12.7	17.0

1. When ordering, please specify screening code:

MS619PYA612MSZ

Screening: Z = Unscreened

Y = Unscreened (SLDC Option A)

W = Unscreened (SLDC Option B)

H = Group A screening per Coilcraft CP-SA-10001

G = Coilcraft CP-SA-10001 Group A (SLDC Option A)

D = Coilcraft CP-SA-10001 Group A (SLDC Option B)

All screening performed to the document's latest revision

Custom screening also available

- 2. Inductance tested at 100 kHz, 0.1 Vrms using an Agilent/HP 4192A.
- 3. DCR measured using a micro-ohmmeter.
- 4. SRF measured using an Agilent/HP 4395A or equivalent.
- 5. DC current at 25°C that causes an inductance drop of 30% (typ) from its value without current.
- 6. Current that causes the specified temperature rise from 25°C ambient. This information is for reference only and does not represent absolute maximum ratings.
- 7. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.

Irms Testing

Irms testing was performed on a 0.060" thick pcb with 4 oz. copper traces optimized to minimize additional temperature rise.

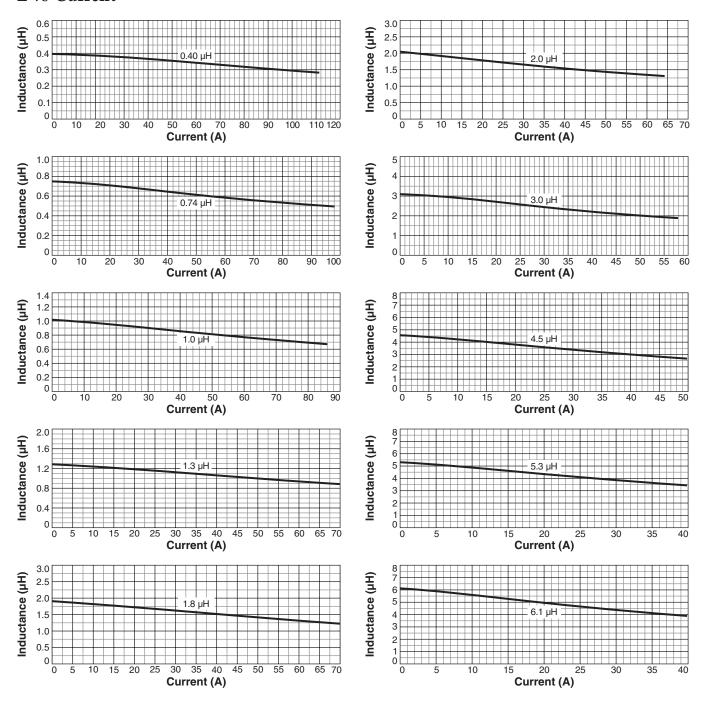
Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.



Document MS891-1 Revised 05/02/23

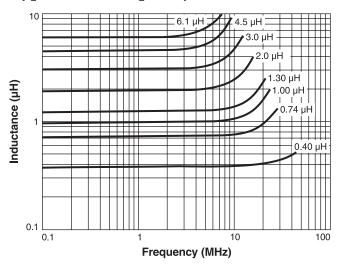
MS619PYA Series (1580)

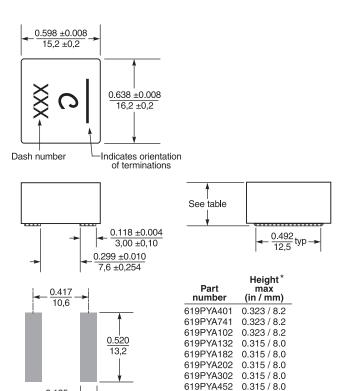
L vs Current



MS619PYA Series (1580)

Typical L vs Frequency





Dimensions are in $\frac{\text{inches}}{\text{mm}}$

0.125

3,18

Suggested Land Pattern

* Height dimension shown is for the mounted part after reflow. Dimension before mounting can be an additional 0.008 inch / 0,2 mm.

619PYA612 0.315 / 8.0

0.315 / 8.0

619PYA532



Cary, IL 60013